

1st IEEE CHIPS SUMMIT DRESDEN

MAY 14 + 15, 2025

 chipssummit.org

in conjunction with
10th IEEE 6G Summit Dresden

Presented by:



PATRONAGE & EXHIBITION OPTIONS

Be part of the first IEEE Chips Summit Dresden 2025 on May 14-15 at [Messe Dresden!](#) This two-day event unites industry leaders, academic pioneers, and tech enthusiasts to explore the forefront of chip technology. Organized by IEEE, 5G Lab Germany, TU Dresden, and the Barkhausen Institut, the Summit features insightful talks and cutting-edge demos from global experts and innovative startups. Join us to discover emerging trends, discuss breakthrough ideas, and uncover new business opportunities shaping the future of chips.



Exhibition at 6G Summit 2023 © Frank Grätz/5G Lab GmbH



5G Lab Germany vision talk at 5G++ Summit 2022
© Frank Grätz/5G Lab GmbH

Patrons and Exhibitors will get visibility at both IEEE 6G Summit and IEEE Chips Summit due to many combined program parts, especially the shared exhibition and the Gala Dinner on May 14th. Participants are invited to join all parts of both events.

To arrange your individual patronage package, please contact:

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**PATRONAGE
OPTIONS ***

	DIAMOND 17,500 EUR	PLATINUM 12,000 EUR	GOLD 7,000 EUR	SILVER 4,500 EUR	BRONZE 2,500 EUR	EXHIBITION BOOTH SPECIAL	
						5,000 EUR	2,500 EUR
Number of complimentary registrations	10	8	6	4	2	5	2
Number of invitations to VIP Dinner (invite only)	2	2	1	1	1		
Size of the exhibition booth at the conference	18 m ²	12 m ²	6 m ²			12 m ²	6 m ²
Logo displayed on conference website							
Logo displayed on banners, conference materials, and between session							
Company rollup and flyer in the entrance hall							
Acknowledgement by Chairperson during welcome session							
Company flag in front of the venue							
Logo printed on the conference lanyard							
Social Media acknowledgement on LinkedIn and X							
Presentation of a Best Exhibition Award							

* Individual packages in general and special packages for academics and startups are possible